

NOVELLUS, ATMI AND ENTHONE INTRODUCE ENHANCED ELECTROCHEMICAL DEPOSITION PROCESS FOR COPPER

DANBURY, Conn. -- March 17, 2009 - Novellus Systems (NASDAQ: NVLS), ATMI, Inc.

(NASDAQ:ATMI), and Enthone Inc. today introduced ViaForm® Extreme Pura™, a new copper deposition process and chemistry for manufacturing advanced copper interconnects at 32 nanometers (nm) and beyond. This new process technology provides a high degree of process control, enables a more robust interconnect fill capability and ensures greater device reliability.

The process was developed through a three-way partnership among Novellus, a provider of advanced process equipment for the global semiconductor industry, ATMI, and Enthone, a manufacturer and developer of high performance semiconductor products. Through an agreement with Enthone, ATMI markets and distributes ViaForm Extreme Pura worldwide for exclusive use on Novellus' market leading SABRE® Electrochemical Deposition product line. ViaForm Extreme Pura is available for immediate use.

In 2003, ATMI and Enthone formed a partnership to develop and distribute state-of-the-art electrochemistries to meet the developing need for manufacturing advanced copper interconnects. Since then, the ViaForm family of plating chemistries and the Novellus SABRE system have consistently met the stringent performance, uniformity, and device yield parameters required by the world's leading manufacturers of copper chips.

"Novellus is focused on providing innovative solutions to the industry's most challenging copper extendibility problems," said Dr. Andrew McKerrow, director of technology for Electrofill at Novellus Systems. "The Pura chemistry has demonstrated improved fill and defect performance at beta customer sites and allows customers to extend their existing technology to the next generation while minimizing cost."

"It's critical for us to meet the unique manufacturing requirements of our semiconductor customers," said Mike Besnard, ATMI Materials director of marketing. "We provide the ability to create copper films that are of high purity, have low defectivity, and consistently deliver the performance and yield that our customers require."

"At 32 nm, copper plating is a critical technology for both memory and logic devices," said Richard Hurtubise, global product line manager - semiconductor products, Enthone. "ViaForm Extreme Pura has a clear advantage in that it meets the demands of shrinking device geometries while giving chip manufacturers the flexibility to apply this chemistry to their existing processes and installed base of Novellus SABRE systems."

About Novellus

Novellus Systems, Inc. (Nasdaq: NVLS) is a leading provider of advanced process equipment for the global semiconductor industry. The company's products deliver value to customers by providing innovative technology backed by trusted productivity. An S&P 500 company, Novellus is headquartered in San Jose, Calif., with subsidiary offices around the globe. For more information, please visit www.novellus.com.

About ATMI

ATMI provides specialty materials and high-purity materials handling and delivery solutions to the worldwide semiconductor industry. For more information, please visit <http://www.atmi.com>.

About Enthone

Enthone Inc. is a business of Cookson Electronics. The company is a leading supplier of high performance specialty chemicals and coatings used in the electronics and surface finishing industries. Enthone manufactures, markets and distributes its functional, decorative and electronic processes that are used in printed wiring board, semiconductor, photovoltaic, automotive, aerospace, jewelry and plumbing applications.

About Cookson Electronics

Cookson Electronics is a leading materials science company that provides high performance materials, chemistry, and technology solutions to the electronics and surface finishing industries worldwide. The company delivers superior value by providing truly differentiated products, services and support through its Alpha, Enthone and Cookson Electronics - Semiconductor Products businesses. For more information, please visit www.cooksonelectronics.com.

"Safe Harbor" Statement

Statements contained herein that relate to ATMI's future performance, including, without limitation, statements with respect to ATMI's anticipated results of operations or level of business for 2008 or any other future period, are forward-looking statements within the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Such statements are based on current expectations only and are subject to certain risks, uncertainties, and assumptions, including, but not limited to, changes in semiconductor industry growth (including, without limitation, wafer starts) or ATMI's markets; competition, problems, or delays developing, commercializing and delivering new products; problems or delays in integrating acquired operations and businesses; uncertainty in the credit and financial markets; and other factors described in ATMI's Form 10-K for the year ended December 31, 2007, and other subsequent filings with the Securities and Exchange Commission. Such risks and uncertainties may cause actual results to differ materially from those expressed in our forward-looking statements. ATMI undertakes no obligation to update any forward-looking statements.

SABRE and Electrofill are registered trademarks, and SABRE Extreme is a trademark of Novellus Systems, Inc. ATMI and the ATMI logo are trademarks or registered trademarks of Advanced Technology Materials, Inc., in the United States, other countries or both. ViaForm is a registered trademark and Pura is a trademark of Enthone Inc.

<https://newsroom.lamresearch.com/2009-03-17-NOVELLUS,-ATMI-AND-ENTHONE-INTRODUCE-ENHANCED-ELECTROCHEMICAL-DEPOSITION-PROCESS-FOR-COPPER>